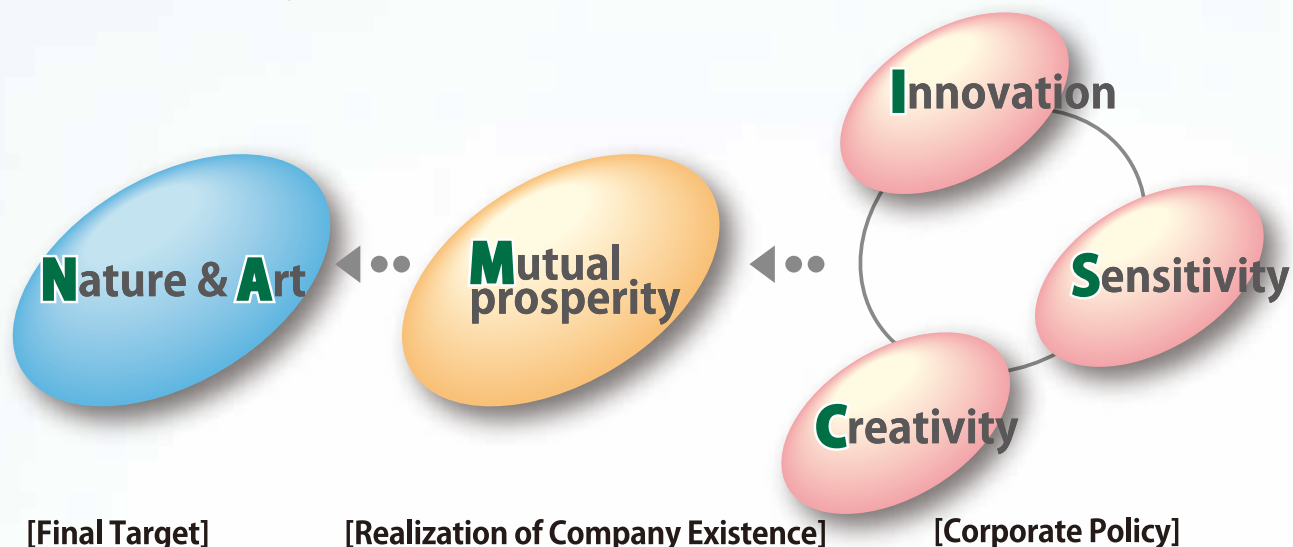




company profile

The name **NAMICS** represents our dream of coexistence and co-prosperity of humans and the natural world.



We envision a future in which our technology will have led to a society that fosters the coexistence of humans and the natural world.

Mutual prosperity is the basis of our management philosophy ; indeed it is our Company's raison d'etre. Our ultimate goal is art in the service of nature , leading to harmonious and advantageous coexistence between humans and the nature world.

The name NAMICS is an acronym of our principles , embodying the idea that sensitivity, innovation and creativity are essential if our goals are to be achieved.



# SEEDS to Explore the Electronics Future



S·E·E·D·S

Developing high-quality, cutting-edge materials to lead the next generation, new possibility will come up in the future of electronics.

**S**  
Semiconductor

Die-attach Materials  
Encapsulant Materials

**E**  
Environment

Adhesive of Low Temperature/UV Curing  
Electrodes of Low Temperature Sintering

**E**  
Energy

Electrodes for Solar Cells

**S**  
System

Composite Materials  
Materials to Meet the Customer Requirements  
Materials to Take Account of Customers Process Advantages

**D**  
Device

Device  
Adhesives for various modules

## NAMICS R&D Concept, SEEDS;

Seeds, disseminated in new earth, can sprout and bring us abundant harvest only when all the environmental conditions are harmonized. For Namics, Seeds means requirements from customers and through them "Growth" of our own. Based on the development and manufacture of insulating and conductive materials, we will focus on new sprout of seeds categorized in five growing areas of "S·E·E·D·S", in cooperation with all division members. We believe that to yield new technological values is our corporate mission through satisfying not only our customers but also the society as a whole.

# Reliable Business with Excellent R&D Capabilities to Keep Fulfilling Wants and Needs of Customers

Based on our cutting edge technologies and reliable business performance, we will make every effort to work on new product development as well as to offer our customers new materials in order to live up to their expectations.

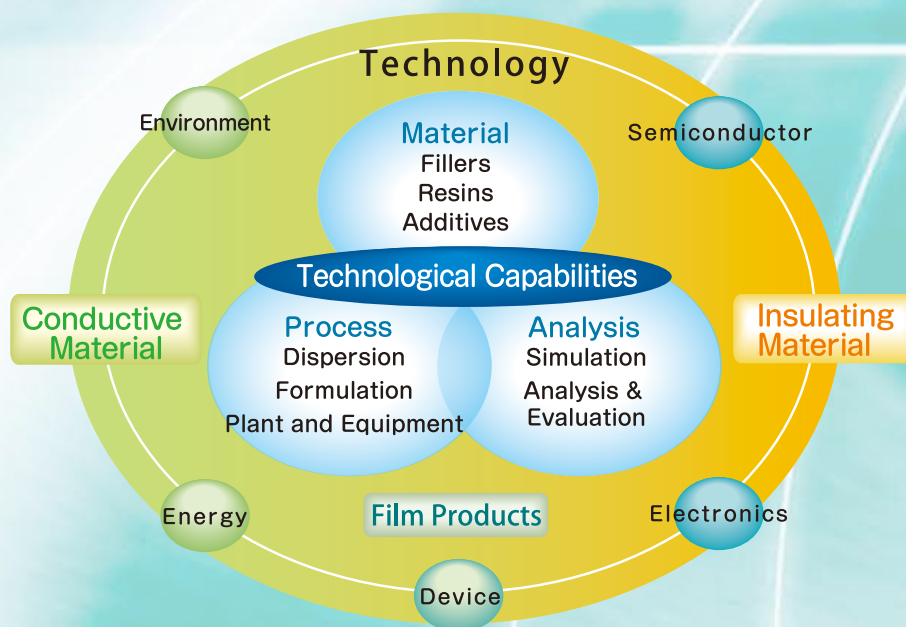
We will actively work on advanced technology development for the realization of customers' wants and needs.

Through sophisticating our material techniques which we have developed since the foundation, and strengthening new material development, we would like to provide the customers with products to realize their potential needs. In collaboration with them, we will develop the products to actively lead the change, and will contribute to create new values of technologies.



Working thoroughly on R&D, Process, and Analysis enables us to create distinctive technology.

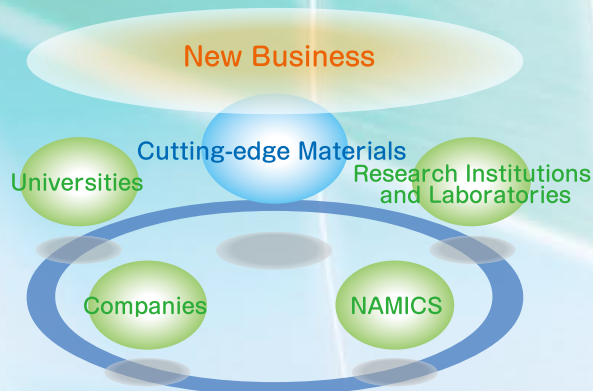
We are developing materials for conductive, insulating, as well as film materials, through utilizing the accumulated expertise and techniques by technologies for Materials/Process/Analysis. Those developed materials are proposed and suggested to the customers in the area of electronic devices, semiconductors, device, energy, and environment, seeking upgrade materials and products.



## Collaboration with Industry, Educational Institutions and the Administration

### Creation of New Business Collaborative Research Promoted by Industry, Educational Institutions and the Administration

New products which have been developed in recent years accounts for 40% of our sales. It is because we always try to fulfill customers' wants and needs, and keep offering new ideas and proposals to the market. In addition, we have been working on the R&D for adhesives to replace with solder, and for nano powders as well as ceramic dielectric powders. We have already achieved good results in this field.



# Series of Namics Products to Pursue the Best Solution by Our Own Technologies

## Insulating Products

**CHIPCOAT®** : High purity insulating materials to serve as an encapsulant for semiconductor chips

### 1. Underfills

UFs are encapsulant materials for Flip chip packages. Dispensed alongside the chip and penetrated between the chips and the substrates after bump connection. They are capillary flow type, and excellent in terms of dispensability and various reliabilities. COF, Chip-on-Film is available which has the ability to fill fine gaps and provides outstanding moisture resistance in IC assembly of LCD driver.

### 2. Glob Top

Glob Top materials are an encapsulant to protect ICs and components, which can be used for CSP/BGA. They have excellent dispensability and moldability.

**OVERCOAT** : An insulating material that acts as a protective coating (G2) for chip resistors. This material has excellent printability and moisture resistance.

### 3. Die Attach Adhesives

Die attach adhesive is an insulator that is dispensed in a pattern, and is used to bond the opposite side of the circuit on an IC chip, which has conductive bumps, to a mounting substrate.

### 4. Adhesives with Various Functionality

You can choose from our wide selection: UV cure type, B stage type, low temperature cure type, and so on.

## Conductive Materials

**HIMEC®** : Sintering type Conductive Pastes

### 1. Pastes for Internal Electrodes of Passive Components

These electro-conductive pastes are sintered to suit specific processes, and are used for internal electrodes of passive components for surface mounting, such as MLCCs and inductors. We are working to achieve lead-free products.

### 2. Front/Back side Electrodes for Solar Cells

These electro-conductive pastes are sintered to suit specific processes, and are used for bus and finger electrodes on the surface of solar cells, and TAB electrodes on the underside.

**UNIMEC®** : Thermosetting Conductive Pastes

### 1. Pastes for Terminal Electrodes of Passive Components

These electro-conductive pastes are sintered to suit specific processes, and are used for terminal electrodes of passive components for surface mounting, such as resistors, MLCCs and inductors.

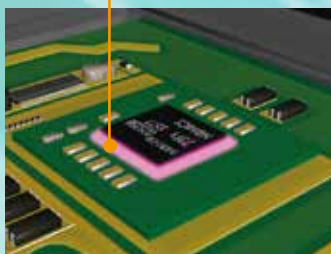
### 2. Surface Mounting Adhesives (Replacement for solder)

These are thermal-cured conductive adhesives that are resistant to high-temperature solder reflow, and can be processed at low temperatures to accommodate lead-free mounting.

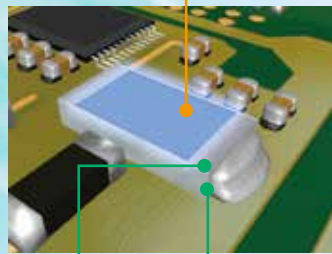
### 3. Die Attach Adhesives (for Semiconductors)

These conductive adhesives are thermal-cured to accommodate various applications, including die bonding, LED bonding, lead bonding, and have high thermal conductivity.

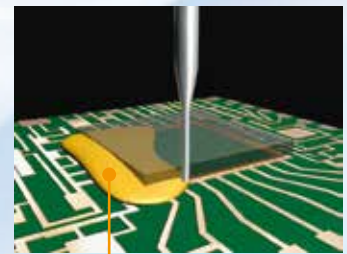
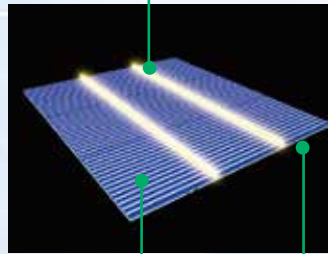
Secondary Underfill Materials



Overcoat



Ag Paste for Bus Electrode



Himec Ag

Unimec Plating Ground

Ag Paste for Finger Electrode

Ag Paste for TAB Electrodes on the Underside

UF Materials for Flip Chip



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